



Materials Declaration Form


IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	21-04-2020
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	MDG MD CHAMPION	Representative Title	MDG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement	
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Legal Statement	
Supplier Acceptance *	true
	Legal Declaration *
	Standard
Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ST7FLIT15BF0M6TR	94Z7*829XXX3	A	959	21-04-2020
	Amount	UoM	Unit type	ST ECOPACK Grade
	500.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SON	NAC	20	Gull Wing	
Comment	Package : Z7 SO 20 .30 TO JEDEC MS-013 0016022			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-16th January 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	94Z7*829XXX3				6000000.0	999999.9
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	7.979	mg	supplier	die	Silicon (Si)	7440-21-3		7.766	mg	973305	15532
				supplier	metallization	Copper (Cu)	7440-50-8		0.174	mg	21807	348
				supplier	metallization	Titanium (Ti)	7440-32-6		0.007	mg	877	14
				supplier	Passivation	Silicon Nitride	12033-89-5		0.008	mg	1003	16
				supplier	Passivation	Silicon Oxide	7631-86-9		0.024	mg	3008	48
Lead-frame	M-011 Other inorganic materials	151.921	mg	supplier	alloy	Copper (Cu)	7440-50-8		148.047	mg	974500	296094
				supplier	alloy	Iron (Fe)	7439-89-6		3.564	mg	23460	7128
				supplier	alloy	Zinc (Zn)	7440-66-6		0.182	mg	1200	365
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.128	mg	840	255
Die Attach	M-011 Other inorganic materials	2.170	mg	supplier	glue or soft solder	Silver (Ag)	7440-22-4		1.855	mg	855000	3711
				supplier	glue or soft solder	Dodecyl acrylate	2156-97-0		0.054	mg	25000	108
				supplier	glue or soft solder	methylene diacrylate	42594-17-2		0.174	mg	80000	347
				supplier	glue or soft solder	Diglycidylphenyl glycidyl ether	13561-08-5		0.043	mg	20000	87
				supplier	glue or soft solder	Isobornyl Methacrylate	7534-94-3		0.022	mg	10000	43
				supplier	glue or soft solder	dimethylbenzyl peroxide	80-43-3		0.022	mg	10000	43
Wires	M-011 Other inorganic materials	0.863	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		0.863	mg	1000000	1726
Encapsulation	M-011 Other inorganic materials	334.454	mg	supplier	Moulding Compound	Silica, vitreous	60676-86-0		292.556	mg	874726	585112
				supplier	Moulding Compound	Epoxy resin	Proprietary		30.154	mg	90159	60308
				supplier	Antimony/Antimony Compounds	Phenol resin	Proprietary		10.067	mg	30098	20133
				supplier	Brominated Flame Retardants (other than	Carbon black	1333-86-4		1.678	mg	5016	3356
Finishing	M-011 Other inorganic materials	2.613	mg	supplier	connections coating	Tin (Sn)	7440-31-5		2.613	mg	1000000	5225

